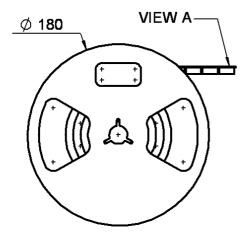
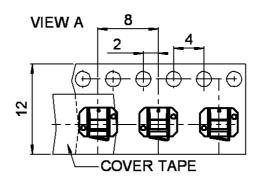
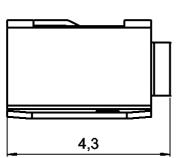
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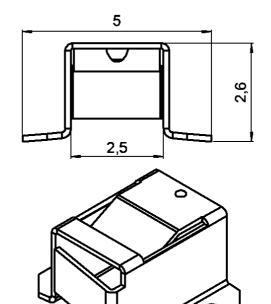
Series: UMP

REEL 100









SCALE: 1/1

All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (µm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	- BERYLLIUM COPPER	GOLD 0.2 OVER NICKEL 2

Issue: 0417 B



R107.103.040

REEL 100

Series: UMP

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50 Ω

Frequency **0-6** GHz

VSWR 1.05 + 0.030 x F(GHz) Maxi

Insertion loss $NA \sqrt{F(GHz)} dB Maxi$

RF leakage - (NA - F(GHz)) dB Maxi

Voltage rating100Veff MaxiDielectric withstanding voltage350Veff miniInsulation resistance1000MΩ mini

ENVIRONMENTAL

Operating temperature -40/+125 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction NA

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end - N mini
Axial force – Opposite end - N mini
Torque - N.cm mini

Recommended torque

Mating - N.cm
Panel nut - N.cm

Mating life 100 Cycles mini

Weight **0.049** g

Issue: 0417 B



R107.103.040

REEL 100

Series: UMP

SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

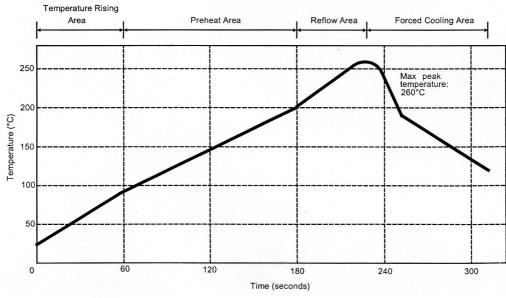
1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

NOTE: THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.

TEMPERATURE PROFIL



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0417 B



REEL 100

R107.103.040

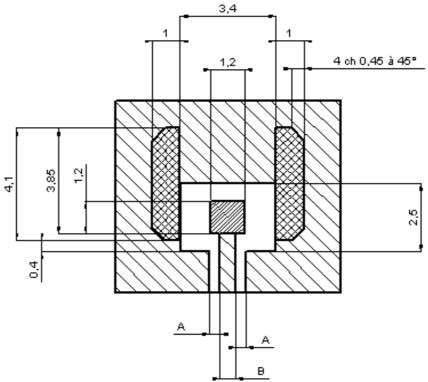
Series: UMP

UMP SERIES INFORMATION

PCB

COPLANAR LINE

Ground and signal are on the same side The material of PCB is glass is glass-epoxy Composite.



Gold over nickel for solder paste

Gold over nickel contact area free of any surface contaminant

Ground + varnish

APPLICATION 75Ω

WITH $B = 0.55$ mm	
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,57
1,0	0,45
1,2	0,41
1.6	0.37

APPILCATION 50Ω

WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,183
1,0	0,190
1,2	0,195
1,6	0,20

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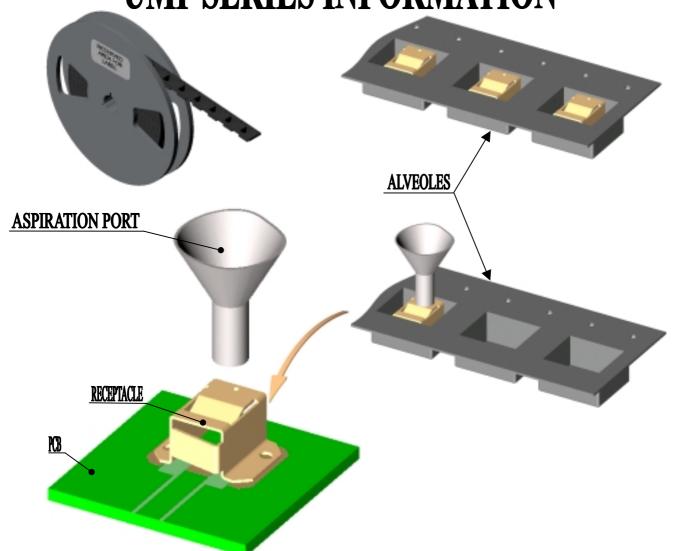


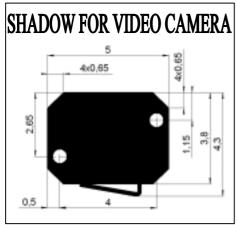
REEL 100

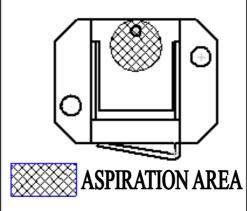
R107.103.040

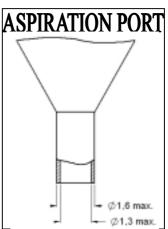
Series: UMP

UMP SERIES INFORMATION









Issue: 0417 B

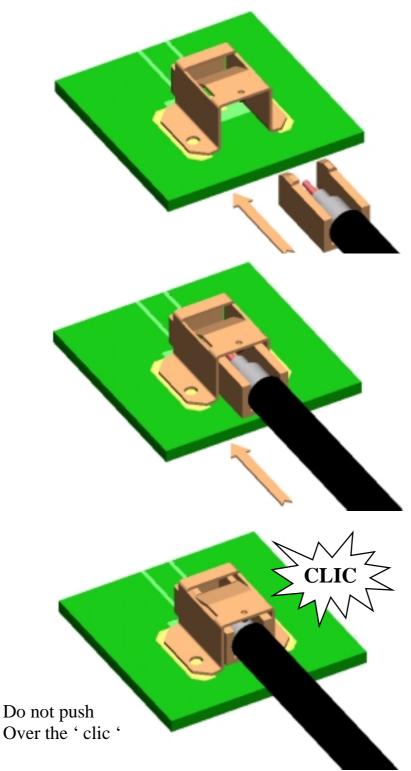


REEL 100

R107.103.040

Series: UMP

UMP CONNECTING NOTE



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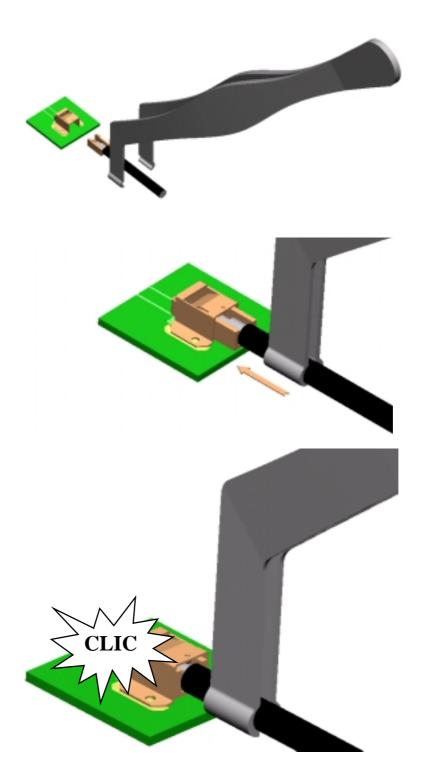


REEL 100

R107.103.040

Series : UMP

UMP CONNECTING NOTE



Do not push Over the 'CLIC'

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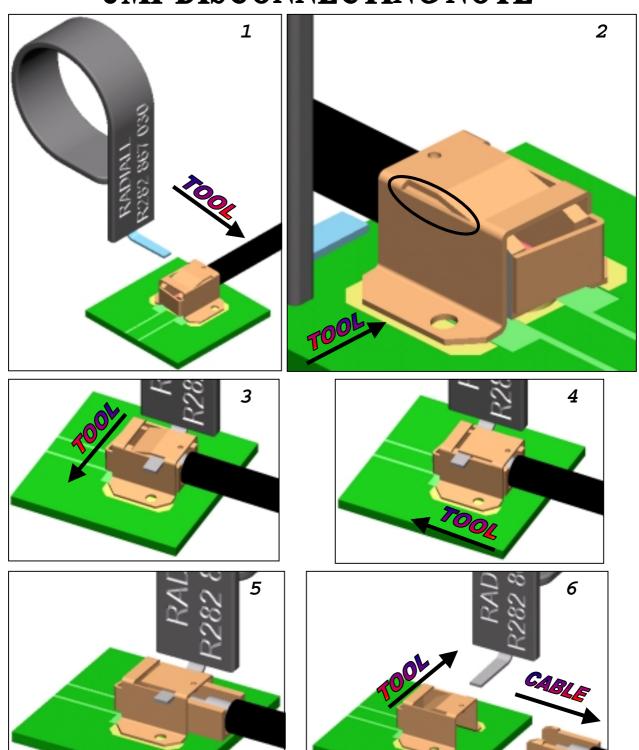


REEL 100

R107.103.040

Series: UMP

UMP DISCONNECTING NOTE



Issue: 0417 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

